

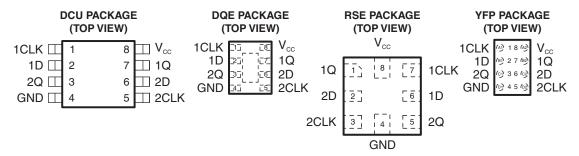
## LOW-POWER DUAL POSITIVE EDGE-TRIGGERED D-TYPE FLIP-FLOP

Check for Samples: SN74AUP2G79

### **FEATURES**

- Available in the Texas Instruments NanoStar™ **Package**
- **Low Static-Power Consumption**  $(I_{CC} = 0.9 \mu A Maximum)$
- Low Dynamic-Power Consumption  $(C_{pd} = 3 pF Typ at 3.3 V)$
- Low Input Capacitance ( $C_i = 1.5 pF Typical$ )
- Low Noise Overshoot and Undershoot <10% of V<sub>CC</sub>
- I<sub>off</sub> Supports Partial-Power-Down Mode Operation
- Wide Operating V<sub>CC</sub> Range of 0.8 V to 3.6 V

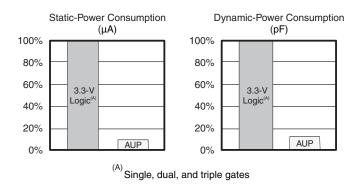
- **Optimized for 3.3-V Operation**
- 3.6-V I/O Tolerant to Support Mixed-Mode **Signal Operation**
- t<sub>pd</sub> = 4 ns Maximum at 3.3 V
- Suitable for Point-to-Point Applications
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- **ESD Performance Tested Per JESD 22** 
  - 2000-V Human-Body Model (A114-B, Class II)
  - 1000-V Charged-Device Model (C101)

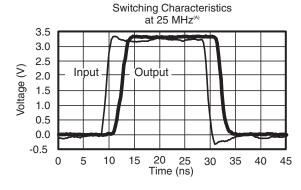


See mechanical drawings for dimensions.

### DESCRIPTION/ORDERING INFORMATION

The AUP family is TI's premier solution to the industry's low-power needs in battery-powered portable applications. This family ensures a very low static- and dynamic-power consumption across the entire V<sub>CC</sub> range of 0.8 V to 3.6 V, resulting in increased battery life (see Figure 1). This product also maintains excellent signal integrity (see the very low undershoot and overshoot characteristics shown in Figure 2).





 $^{(A)}$ SN74AUP2Gxx data at C<sub>I\_</sub> = 15 pF.

Figure 1. AUP - The Lowest-Power Family

Figure 2. Excellent Signal Integrity

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When data at the data (D) input meets the setup time requirement, the data is transferred to the Q output on the positive-going edge of the clock pulse. Clock triggering occurs at a voltage level and is not directly related to the rise time of the clock pulse. Following the hold-time interval, data at the D input can be changed without affecting the levels at the outputs.

NanoStar<sup>™</sup> package technology is a major breakthrough in IC packaging concepts, using the die as the package.

This device is fully specified for partial-power-down applications using  $I_{\text{off}}$ . The  $I_{\text{off}}$  circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

### ORDERING INFORMATION(1)

T <sub>A</sub>	PACKAGE <sup>(2)</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING(3)
	NanoStar™ – WCSP (DSBGA) 0.23-mm Large Bump – YFP (Pb-free)	Reel of 3000	SN74AUP2G79YFPR	HW_
-40°C to 85°C	uQFN – DQE	Reel of 5000	SN74AUP2G79DQER	PT
	QFN - RSE	Reel of 5000	SN74AUP2G79RSER	PT
	SSOP - DCU	Reel of 3000	SN74AUP2G79DCUR	H79_

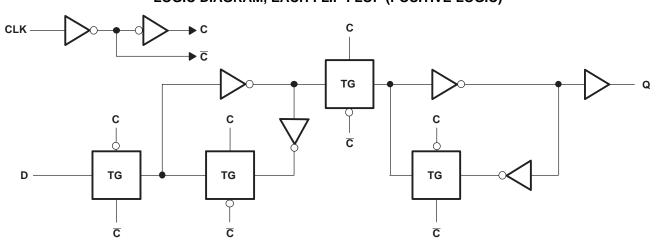
- (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.
- (2) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.
- (3) DCU: The actual top-side marking has one additional character that designates the wafer fab/assembly site.

  YFP: The actual top-side marking has three preceding characters to denote year, month, and sequence code, and one following character to designate wafer fab/assembly site. Pin 1 identifier indicates solder-bump composition (1 = SnPb, = Pb-free).

#### **FUNCTION TABLE**

INPU	TS	OUTPUT
CLK	D	Q
1	Н	Н
<b>↑</b>	L	L
L	X	$Q_0$
Н	X	$Q_0$

## LOGIC DIAGRAM, EACH FLIP-FLOP (POSITIVE LOGIC)



Pin numbers shown are for the DCU and DQE packages.



## **ABSOLUTE MAXIMUM RATINGS**(1)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage range		-0.5	4.6	V
VI	Input voltage range <sup>(2)</sup>		-0.5	4.6	V
Vo	Voltage range applied to any output in the	-0.5	4.6	V	
Vo	Output voltage range in the high or low state	-0.5	V <sub>CC</sub> + 0.5	V	
I <sub>IK</sub>	Input clamp current	V <sub>1</sub> < 0		-50	mA
l <sub>OK</sub>	Output clamp current	V <sub>O</sub> < 0		-50	mA
lo	Continuous output current			±20	mA
	Continuous current through V <sub>CC</sub> or GND			±50	mA
		DCU package		220	
0	Deal and the seal investigation (3)	DQE package		261	00/14/
$\theta_{JA}$	Package thermal impedance (3)	RSE package		253	°C/W
		YFP package		132	
T <sub>stg</sub>	Storage temperature range		-65	150	°C

<sup>(1)</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

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<sup>2)</sup> The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

<sup>(3)</sup> The package thermal impedance is calculated in accordance with JESD 51-7.



## RECOMMENDED OPERATING CONDITIONS(1)

			MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage		0.8	3.6	V
		V <sub>CC</sub> = 0.8 V	V <sub>CC</sub>		
.,	High level input valtage	$V_{CC} = 1.1 \text{ V to } 1.95 \text{ V}$	0.65 × V <sub>CC</sub>		V
$V_{IH}$	High-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.6		V
		$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$	2		
		$V_{CC} = 0.8 \text{ V}$		0	
.,	Law lavel input valtage	$V_{CC} = 1.1 \text{ V to } 1.95 \text{ V}$		$0.35 \times V_{CC}$	V
$V_{IL}$	Low-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7	V
		V <sub>CC</sub> = 3 V to 3.6 V		0.9	
VI	Input voltage		0	3.6	V
Vo	Output voltage		0	$V_{CC}$	V
	High level autout august	V <sub>CC</sub> = 0.8 V		-20	μΑ
		V <sub>CC</sub> = 1.1 V		-1.1	
		V <sub>CC</sub> = 1.4 V		-1.7	
I <sub>OH</sub>	High-level output current	V <sub>CC</sub> = 1.65	V <sub>CC</sub> = 1.65		mA
		$V_{CC} = 2.3 \text{ V}$		-3.1	
		$V_{CC} = 3 V$		-4	
		V <sub>CC</sub> = 0.8 V		20	μΑ
		V <sub>CC</sub> = 1.1 V		1.1	
	Laurelaurelauren aumant	V <sub>CC</sub> = 1.4 V		1.7	
l <sub>OL</sub>	Low-level output current	V <sub>CC</sub> = 1.65 V		1.9	
		V <sub>CC</sub> = 2.3 V			
		V <sub>CC</sub> = 3 V		4	
Δt/Δν	Input transition rise or fall rate	V <sub>CC</sub> = 0.8 V to 3.6 V		200	ns/V
T <sub>A</sub>	Operating free-air temperature		-40	85	°C

<sup>(1)</sup> All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



## **ELECTRICAL CHARACTERISTICS**

over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST COMPLETIONS	V	T <sub>A</sub>	= 25°C	$T_A = -40^{\circ}C$ to 8	5°C	LINUT
PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	MIN	TYP MAX	MIN	MAX	UNIT
	I <sub>OH</sub> = -20 μA	0.8 V to 3.6 V	V <sub>CC</sub> - 0.1		V <sub>CC</sub> - 0.1		
	I <sub>OH</sub> = -1.1 mA	1.1 V	0.75 × V <sub>CC</sub>		0.7 × V <sub>CC</sub>		
	I <sub>OH</sub> = −1.7 mA	1.4 V	1.11		1.03		
. ,	I <sub>OH</sub> = −1.9 mA	1.65 V	1.32		1.3		
V <sub>OH</sub>	$I_{OH} = -2.3 \text{ mA}$	221/	2.05		1.97		V
	I <sub>OH</sub> = -3.1 mA	2.3 V	1.9		1.85		
	$I_{OH} = -2.7 \text{ mA}$	0.1/	2.72		2.67		
	$I_{OH} = -4 \text{ mA}$	3 V	2.6		2.55		
	I <sub>OL</sub> = 20 μA	0.8 V to 3.6 V		0.1		0.1	
	I <sub>OL</sub> = 1.1 mA	1.1 V		0.3 × V <sub>CC</sub>	0.3	× V <sub>CC</sub>	٧
	I <sub>OL</sub> = 1.7 mA	1.4 V		0.31		0.37	
	I <sub>OL</sub> = 1.9 mA	1.65 V		0.31		0.35	
V <sub>OL</sub>	I <sub>OL</sub> = 2.3 mA	2.3 V		0.31		0.33	
	I <sub>OL</sub> = 3.1 mA	2.3 V		0.44		0.45	
	I <sub>OL</sub> = 2.7 mA	3 V		0.31		0.33	
	$I_{OL} = 4 \text{ mA}$	3 V		0.44		0.45	
A or B input	V <sub>I</sub> = GND to 3.6 V	0 V to 3.6 V		0.1		0.5	μΑ
off	$V_I$ or $V_O = 0$ V to 3.6 V	0 V		0.2		0.6	μΑ
ΔI <sub>off</sub>	$V_I$ or $V_O = 0$ V to 3.6 V	0 V to 0.2 V		0.2		0.6	μΑ
lcc	V <sub>I</sub> = GND or (V <sub>CC</sub> to 3.6 V), I <sub>O</sub> = 0	0.8 V to 3.6 V		0.5		0.9	μΑ
ΔI <sub>CC</sub>	$V_I = V_{CC} - 0.6 V^{(1)},$ $I_O = 0$	3.3 V		40		50	μΑ
^	V V or CND	0 V		1.5			~F
C <sub>i</sub>	$V_I = V_{CC}$ or GND	3.6 V		1.5			pF
C <sub>o</sub>	V <sub>O</sub> = GND	0 V		3			pF

<sup>(1)</sup> One input at  $V_{CC}$  – 0.6 V, other input at  $V_{CC}$  or GND



## **TIMING REQUIREMENTS**

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 4)

			V <sub>CC</sub>	T <sub>A</sub> = 25°C	T <sub>A</sub> = -40°C to 85°C	UNIT
				TYP	MIN MAX	
			0.8 V		20	
			1.2 V ± 0.1 V		80	
	Clock from tone		1.5 V ± 0.1 V		100	MHz
f <sub>clock</sub>	Clock frequency		1.8 V ± 0.15 V		140	IVI□Z
			2.5 V ± 0.2 V		210	
			3.3 V ± 0.3 V		260	
·			0.8 V		4.8	
ı			1.2 V ± 0.1 V		2.2	
	5		1.5 V ± 0.1 V		1.5	
t <sub>w</sub>	Pulse duration, CLK high or low		1.8 V ± 0.15 V		1.6	ns
			2.5 V ± 0.2 V		1.7	
			3.3 V ± 0.3 V		1.9	
			0.8 V	2.9	4.2	
			1.2 V ± 0.1 V		1.4	
		5	1.5 V ± 0.1 V		1	
		Data high	1.8 V ± 0.15 V		0.9	
			2.5 V ± 0.2 V		0.7	
			3.3 V ± 0.3 V		0.6	
t <sub>su</sub>	Setup time before CLK↑		0.8 V	3.5	5.3	ns
			1.2 V ± 0.1 V		1.8	
			1.5 V ± 0.1 V		1.2	
		Data low	1.8 V ± 0.15 V		1.1	
			2.5 V ± 0.2 V		1	
			3.3 V ± 0.3 V		1	
			0.8 V	0	0	
			1.2 V ± 0.1 V		0	
			1.5 V ± 0.1 V		0	
t <sub>h</sub>	Hold time, data after CLK↑	Hold time, data after CLK↑			0	ns
			1.8 V ± 0.15 V 2.5 V ± 0.2 V		0	
		3.3 V ± 0.3 V		0		



## **SWITCHING CHARACTERISTICS**

over recommended operating free-air temperature range,  $C_L = 5 \text{ pF}$  (unless otherwise noted) (see Figure 3 and Figure 4)

PARAMETER	FROM	FROM TO NPUT) (OUTPUT)	V <sub>CC</sub>	T,	T <sub>A</sub> = 25°C			T <sub>A</sub> = -40°C to 85°C	
	(INFOT)	(001701)	(OUTPOT)	MIN	TYP	MAX	MIN	MAX	
			0.8 V		93		90		
			1.2 V ± 0.1 V		199		220		
			1.5 V ± 0.1 V		250		230		NAL 1-
<sup>T</sup> max	f <sub>max</sub>		1.8 V ± 0.15 V		271		240		MHz
			2.5 V ± 0.2 V		280		250		
			3.3 V ± 0.3 V		280		260		
			0.8 V		15.9				
			1.2 V ± 0.1 V	3.7	6.9	11	2.6	13.1	
	OL K	0	1.5 V ± 0.1 V	3	4.8	7.6	2	8.8	
t <sub>pd</sub>	CLK	CLK Q	1.8 V ± 0.15 V	2.4	3.8	6.1	1.5	7.1	ns
			2.5 V ± 0.2 V	1.8	2.7	4.4	1.1	5	
			3.3 V ± 0.3 V	1.5	2.1	3.6	0.9	4	

### **SWITCHING CHARACTERISTICS**

over recommended operating free-air temperature range,  $C_L = 10 \text{ pF}$  (unless otherwise noted) (see Figure 3 and Figure 4)

PARAMETER	FROM TO (OUTPUT		V <sub>cc</sub>	T <sub>A</sub> = 25°C			T <sub>A</sub> = -40°C to 85°C		UNIT
		(001701)		MIN	TYP	MAX	MIN	MAX	
			0.8 V		62		50		
			1.2 V ± 0.1 V		147		160		
£			1.5 V ± 0.1 V		189		200		MHz
Imax	f <sub>max</sub>		1.8 V ± 0.15 V		180		240		IVITZ
			2.5 V ± 0.2 V		260		250		
			3.3 V ± 0.3 V		280		260		
			0.8 V		18				
			1.2 V ± 0.1 V	4.3	7.8	12.3	3.2	14.4	
	CLK	0	1.5 V ± 0.1 V	3.5	5.5	8.4	2.5	9.8	
t <sub>pd</sub>	CLK	CLK Q	1.8 V ± 0.15 V	2.8	4.4	6.8	1.9	8	ns
			2.5 V ± 0.2 V	2.2	3.2	5	1.5	5.7	
			3.3 V ± 0.3 V	1.8	2.6	4.1	1.3	4.5	

Product Folder Link(s): SN74AUP2G79



### **SWITCHING CHARACTERISTICS**

over recommended operating free-air temperature range,  $C_L = 15 \text{ pF}$  (unless otherwise noted) (see Figure 3 and Figure 4)

PARAMETER	FROM TO (OUTPUT) V <sub>CC</sub>		V <sub>cc</sub>	T,	<sub>\(\lambda\)</sub> = 25°C		T <sub>A</sub> = -40°C to 85°C		UNIT
			MIN	TYP	MAX	MIN	MAX		
			0.8 V		48		30		
			1.2 V ± 0.1 V		112		120		
4			1.5 V ± 0.1 V		151		160		MHz
f <sub>max</sub>			1.8 V ± 0.15 V		194		220		IVITZ
			2.5 V ± 0.2 V		248		250		
			3.3 V ± 0.3 V		280		260		
			0.8 V		20.3				
			1.2 V ± 0.1 V	5	8.7	13.6	3.9	15.6	
	CLK	0	1.5 V ± 0.1 V	4.1	6.3	9.3	3.1	10.7	20
t <sub>pd</sub>	CLK	Q	1.8 V ± 0.15 V	3.3	4	7.6	2.4	8.7	ns
			2.5 V ± 0.2 V	2.6	3.6	5.5	1.9	6.3	
			3.3 V ± 0.3 V	2.2	3	4.5	1.6	5	

## **SWITCHING CHARACTERISTICS**

over recommended operating free-air temperature range, C<sub>L</sub> = 30 pF (unless otherwise noted) (see Figure 3 and Figure 4)

PARAMETER	FROM TO (OUTPUT)		V <sub>cc</sub>	T <sub>A</sub> = 25°C			T <sub>A</sub> = -40°C to 85°C		UNIT
			MIN	TYP	MAX	MIN	MAX		
			0.8 V		24		20		
			1.2 V ± 0.1 V		72		80		
£ .			1.5 V ± 0.1 V		100		100		MHz
f <sub>max</sub>			1.8 V ± 0.15 V		127		140		IVITZ
			2.5 V ± 0.2 V		185		210		
			3.3 V ± 0.3 V		266		260		
			0.8 V		27.2				
			1.2 V ± 0.1 V	7	11.5	17.3	5.9	24	
	CLK	0	1.5 V ± 0.1 V	5.7	8.3	13.3	4.6	15.9	20
t <sub>pd</sub>	CLK	CLK Q	1.8 V ± 0.15 V	4.7	6.7	11.3	3.8	13	ns
			2.5 V ± 0.2 V	3.7	4.9	7.8	2.9	9	
			3.3 V ± 0.3 V	3.2	4.1	6.3	2.6	7.2	

## **OPERATING CHARACTERISTICS**

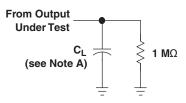
 $T_A = 25^{\circ}C$ 

	PARAMETER	TEST CONDITIONS	V <sub>cc</sub>	TYP	UNIT
			0.8 V	2.5	
			1.2 V ± 0.1 V	2.5	
_	2 40 MIL	f 40 MH =	1.5 V ± 0.1 V	2.5	pF
$C_{pd}$	Power dissipation capacitance	f = 10 MHz	1.8 V ± 0.15 V	2.5	
			2.5 V ± 0.2 V	3	
			3.3 V ± 0.3 V	3	

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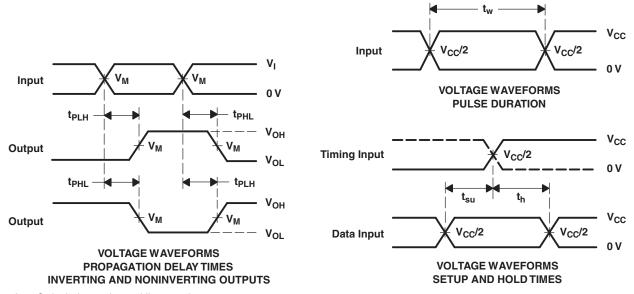


## PARAMETER MEASUREMENT INFORMATION (Propagation Delays, Setup and Hold Times, and Pulse Width)



LOAD CIRCUIT

	V <sub>CC</sub> = 0.8 V	V <sub>CC</sub> = 1.2 V ± 0.1 V	V <sub>CC</sub> = 1.5 V ± 0.1 V	$V_{CC}$ = 1.8 V $\pm$ 0.15 V	$V_{CC}$ = 2.5 V $\pm$ 0.2 V	V <sub>CC</sub> = 3.3 V ± 0.3 V
C <sub>L</sub>	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF
V <sub>M</sub>	V <sub>CC</sub> /2	V <sub>CC</sub> /2	V <sub>CC</sub> /2	V <sub>CC</sub> /2	V <sub>CC</sub> /2	V <sub>CC</sub> /2
V <sub>I</sub>	V <sub>CC</sub>	V <sub>CC</sub>	V <sub>CC</sub>	V <sub>CC</sub>	V <sub>CC</sub>	V <sub>CC</sub>



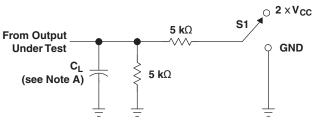
- C<sub>1</sub> includes probe and jig capacitance.
- Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_{O}$  = 50  $\Omega$ , for propagation delays  $t_r/t_f = 3$  ns, for setup and hold times and pulse width  $t_r/t_f = 1.2$  ns.
- The outputs are measured one at a time, with one transition per measurement.
- $t_{\text{PLH}}$  and  $t_{\text{PHL}}$  are the same as  $t_{\text{pd}}$ .
- All parameters and waveforms are not applicable to all devices.

Figure 3. Load Circuit and Voltage Waveforms

Product Folder Link(s): SN74AUP2G79



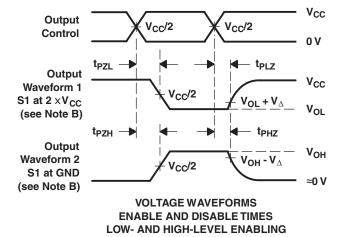
# PARAMETER MEASUREMENT INFORMATION (Enable and Disable Times)



TEST	S1
t <sub>PLZ</sub> /t <sub>PZL</sub>	2×V <sub>CC</sub>
t <sub>PHZ</sub> /t <sub>PZH</sub>	GND

LOAD CIRCUIT

	V <sub>CC</sub> = 0.8 V	V <sub>CC</sub> = 1.2 V ± 0.1 V	V <sub>CC</sub> = 1.5 V ± 0.1 V	V <sub>CC</sub> = 1.8 V ± 0.15 V	$V_{CC}$ = 2.5 V $\pm$ 0.2 V	$V_{CC}$ = 3.3 V $\pm$ 0.3 V
C <sub>L</sub>	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF
V <sub>M</sub>	V <sub>CC</sub> /2	V <sub>CC</sub> /2	V <sub>CC</sub> /2	V <sub>CC</sub> /2	V <sub>CC</sub> /2	V <sub>CC</sub> /2
V <sub>I</sub>	V <sub>CC</sub>	V <sub>CC</sub>	V <sub>CC</sub>	V <sub>CC</sub>	V <sub>CC</sub>	V <sub>CC</sub>
V <sub>∆</sub>	0.1 V	0.1 V	0.1 V	0.15 V	0.15 V	0.3 V



- A. C<sub>L</sub> includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \Omega$ ,  $t_f/t_f = 3$  ns.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. t<sub>PLZ</sub> and t<sub>PHZ</sub> are the same as t<sub>dis</sub>.
- F.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
- G. All parameters and waveforms are not applicable to all devices.

Figure 4. Load Circuit and Voltage Waveforms

Submit Documentation Feedback





## **REVISION HISTORY**

Cł	hanges from Revision B (March 2010) to Revision C	Page
•	Added clock high to FUNCTION TABLE.	2

Product Folder Link(s): SN74AUP2G79





10-Dec-2020

### PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74AUP2G79DCUR	ACTIVE	VSSOP	DCU	8	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	H79R	Samples
SN74AUP2G79DQER	ACTIVE	X2SON	DQE	8	5000	RoHS & Green	NIPDAUAG	Level-1-260C-UNLIM	-40 to 85	PT	Samples
SN74AUP2G79RSER	ACTIVE	UQFN	RSE	8	5000	RoHS & Green	NIPDAUAG	Level-1-260C-UNLIM	-40 to 85	PT	Samples
SN74AUP2G79YFPR	ACTIVE	DSBGA	YFP	8	3000	RoHS & Green	SNAGCU	Level-1-260C-UNLIM	-40 to 85	HWN	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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## **PACKAGE OPTION ADDENDUM**

10-Dec-2020

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## PACKAGE MATERIALS INFORMATION

www.ti.com 18-Jan-2020

## TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



### \*All dimensions are nominal

All differsions are norminal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AUP2G79DCUR	VSSOP	DCU	8	3000	180.0	8.4	2.25	3.35	1.05	4.0	8.0	Q3
SN74AUP2G79DQER	X2SON	DQE	8	5000	180.0	8.4	1.2	1.6	0.55	4.0	8.0	Q1
SN74AUP2G79RSER	UQFN	RSE	8	5000	180.0	8.4	1.7	1.7	0.7	4.0	8.0	Q2
SN74AUP2G79YFPR	DSBGA	YFP	8	3000	178.0	9.2	0.9	1.75	0.6	4.0	8.0	Q1

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\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AUP2G79DCUR	VSSOP	DCU	8	3000	202.0	201.0	28.0
SN74AUP2G79DQER	X2SON	DQE	8	5000	202.0	201.0	28.0
SN74AUP2G79RSER	UQFN	RSE	8	5000	202.0	201.0	28.0
SN74AUP2G79YFPR	DSBGA	YFP	8	3000	220.0	220.0	35.0

# DCU (R-PDSO-G8)

## PLASTIC SMALL-OUTLINE PACKAGE (DIE DOWN)



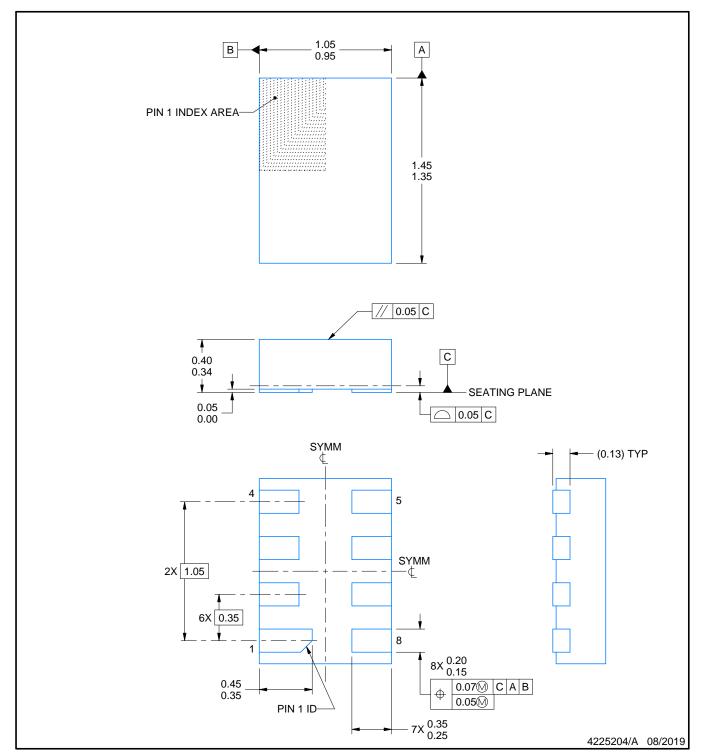
NOTES:

- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
  - D. Falls within JEDEC MO-187 variation CA.





PLASTIC SMALL OUTLINE - NO LEAD



### NOTES:

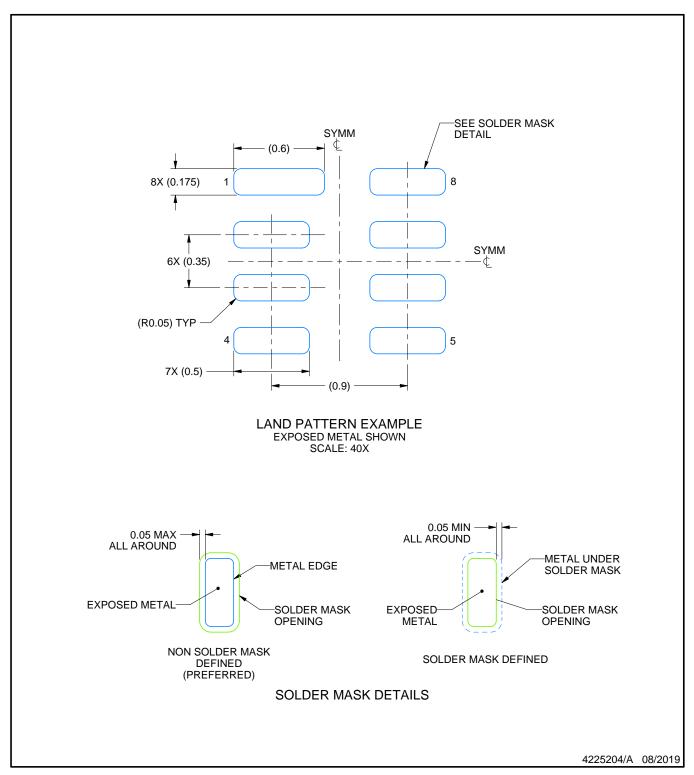
- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This package complies to JEDEC MO-287 variation X2EAF.



PLASTIC SMALL OUTLINE - NO LEAD

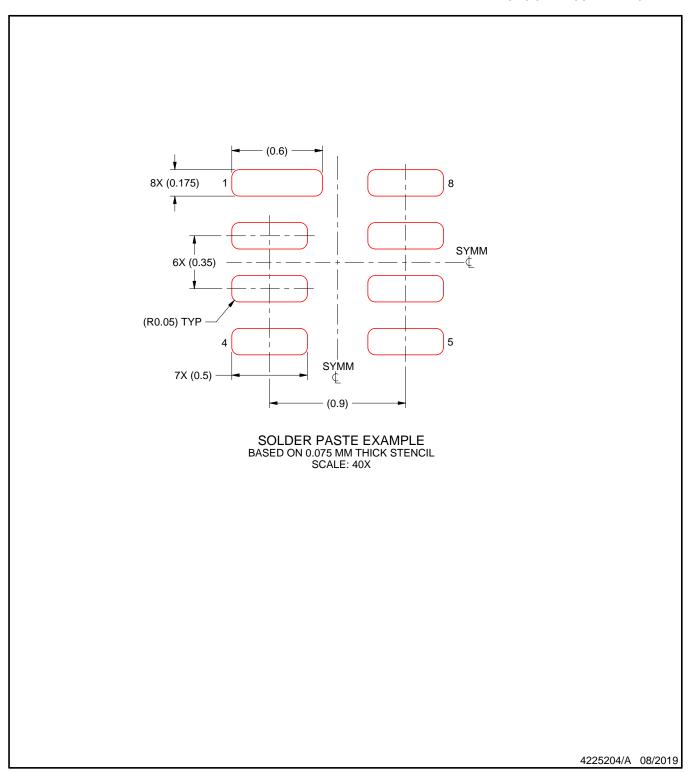


NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).



PLASTIC SMALL OUTLINE - NO LEAD



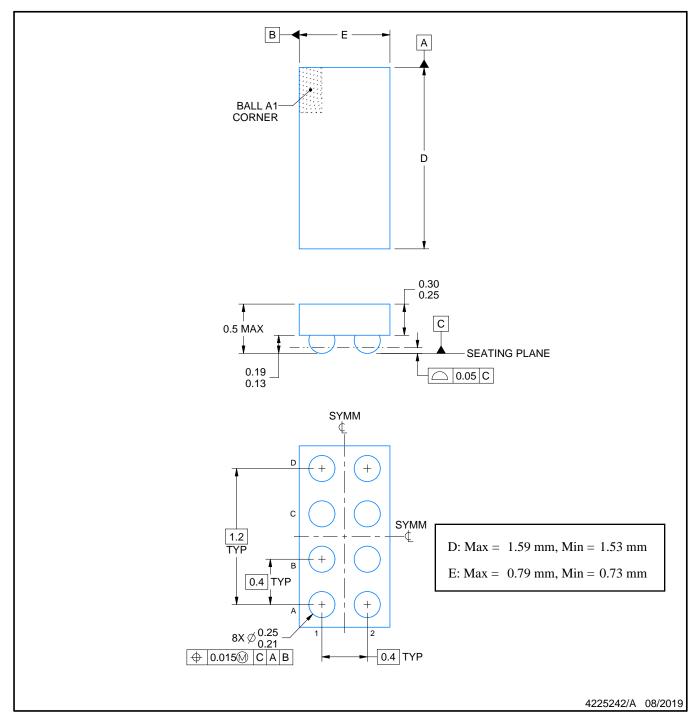
NOTES: (continued)

5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.





DIE SIZE BALL GRID ARRAY



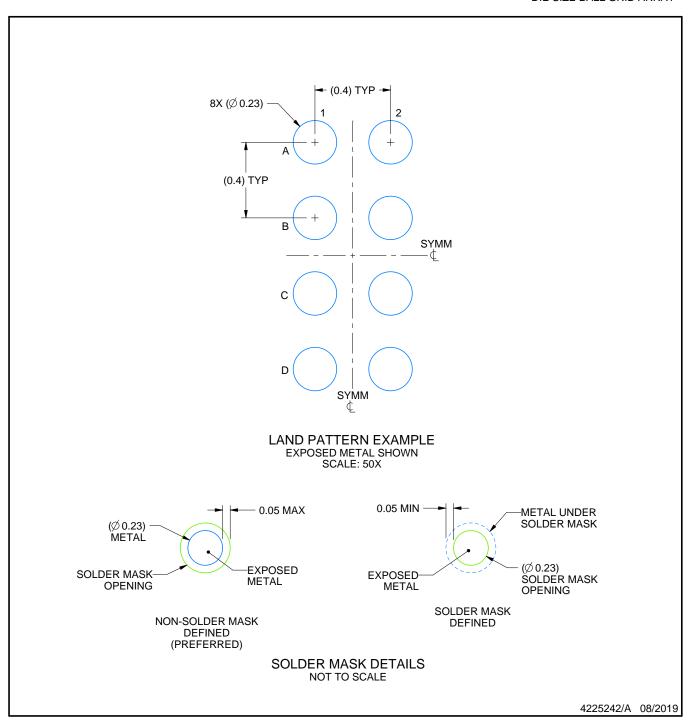
### NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.



DIE SIZE BALL GRID ARRAY

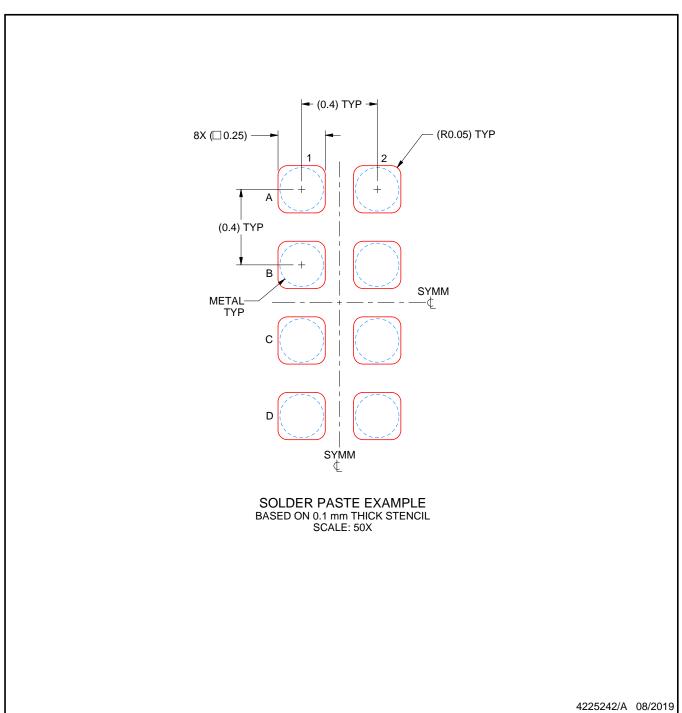


NOTES: (continued)

Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. See Texas Instruments Literature No. SNVA009 (www.ti.com/lit/snva009).



DIE SIZE BALL GRID ARRAY



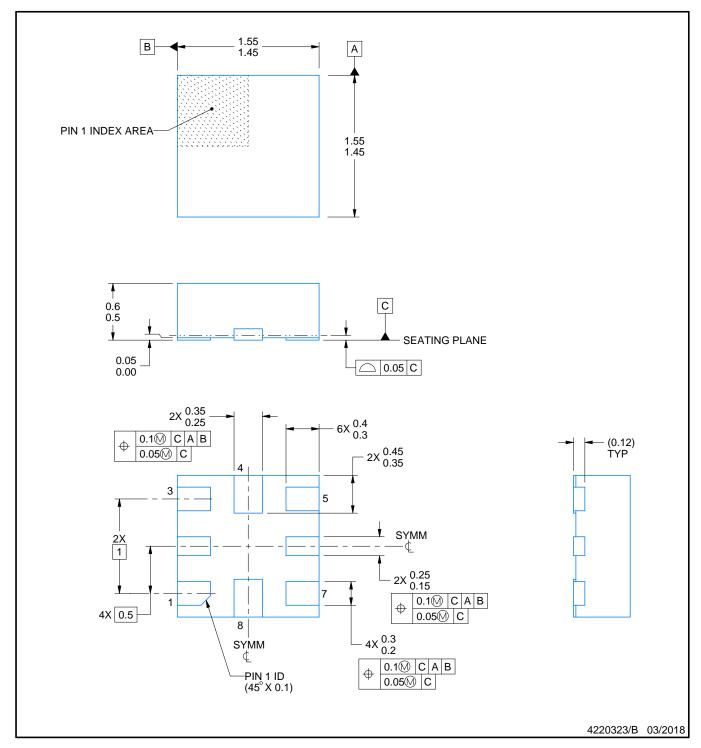
### NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.





PLASTIC QUAD FLATPACK - NO LEAD

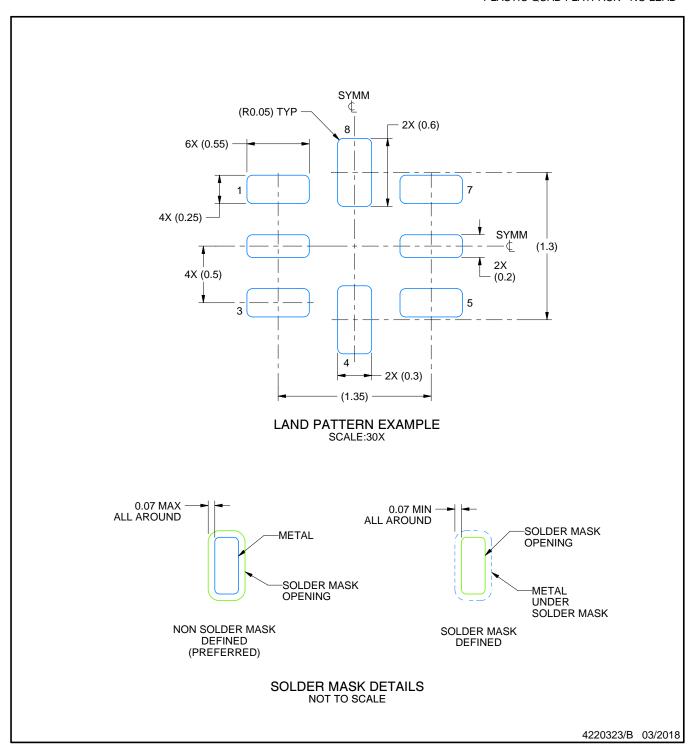


### NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.



PLASTIC QUAD FLATPACK - NO LEAD

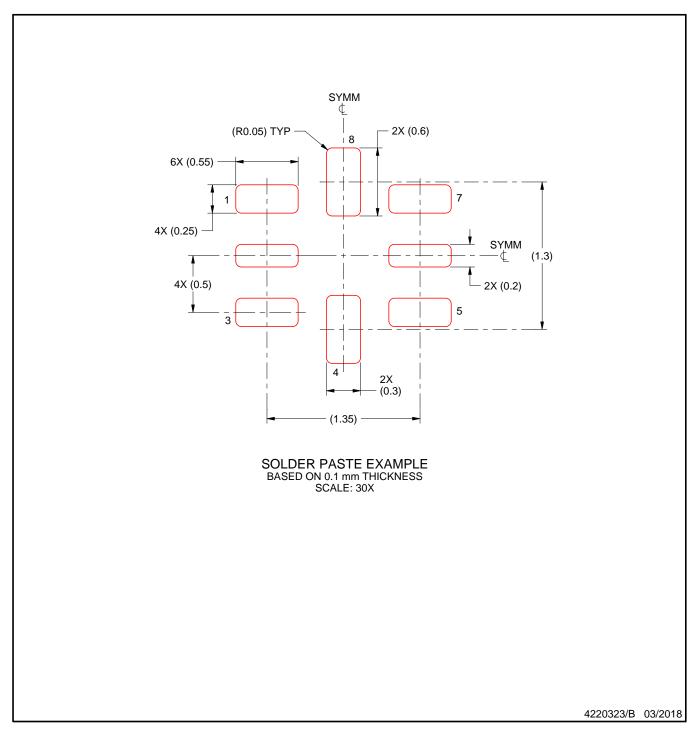


NOTES: (continued)

3. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).



PLASTIC QUAD FLATPACK - NO LEAD



NOTES: (continued)

5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.



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